



PRODUCT DESCRIPTION

At 6.4 W/m-K thermal conductivity, Tflex™ CR607 is at the forefront of thermal performance for a two-part, cure in place dispensable gap filler. This dispensable gap filler minimizes stress on components during assembly while providing the reliability of a traditional thermal pad. Tflex™ CR607 has been designed for reliability, intended to pass stringent vertical shock and vibe requirements of the automotive industry.

The 1:1 mix is dispensable through a wide variety of dispensing equipment. It is an A+B putty material that cures in place after dispensing and mixing to perfectly fill the gap. The experts at Laird can help design the system that is right for you.

Tflex™ CR607 is a soft, compliant, high thermal conductivity dispensable gap filler providing the lowest thermal resistance and highest reliability available.

FEATURES AND BENEFITS

- Thermal Conductivity 6.4W/mK
- Dispensable and Compliant
- Easily reworkable
- Ideal for large gaps
- Meets ROHS and REACH requirements

APPLICATIONS

- Telecom base stations
- Graphic chips
- Microprocessors
- High-power automotive electronic controls

MAIN PROPERTIES

TYPICAL PROPERTIES	VALUE	TEST METHOD
Composition	Two-part ceramic filled dispensable silicone gap filler	
Color	Part A: Blue Part B:White	Visual
Flow rate (75cc taper tip, 0.125" orifice, at 90psi)	70 g/min	Laird Method
Pot life	1 hour minimum	Laird Method
Mix ratio	1:1	
Shelf Life	6 months	Laird Method
Cure conditions	24 hours at 25°C	Laird Method
PROPERTIES AFTER CURING		
Thermal Conductivity	6.4 W/mK	Hot Disk
Density	3.43 g/cc	Helium Pycnometer
Hardness (30sec)	70 Shore 00	ASTM D2240
Outgassing TML (weight)	0.11 %	ASTM E595

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THR-DS-Tflex™ CR607_06102024

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PROPERTIES AFTER CURING		CONTINUED
TYPICAL PROPERTY	VALUE	TEST METHOD
Minimum Bond Line Thickness	150 µm	Laird Method
Operating Temperature Range	-55°C to 200°C	
Thermal Resistance at 1mm, 50°C, 345kPa	2.15 °C·cm²/W	ASTM D5470 (Modified)
Dielectric Breakdown Voltage at 2mm	6 kV AC	ASTM D149
UL Flammability Rating	V-0 (pending)	UL
Volume Resistivity	2.5 x 10 ¹⁴ ohm·cm	ISO 14309

PACKAGING

TYPE	FILL VOLUME	FILL WEIGHT
50cc side-by-side cartridge (2x25cc)	48 cc	160 g
200cc side-by-side cartridge (2x100cc)	215 cc	730 g
400cc side-by-side cartridge (2x200cc)	394 cc	1340 g
1-gallon pail x2	4070 cc x2	14kg x2
5-gallon pail x2	5820 cc x2	20kg x2

SAMPLING

TYPE	FILL VOLUME	FILL WEIGHT
50cc side-by-side cartridge (2x25cc)	48cc	160 g